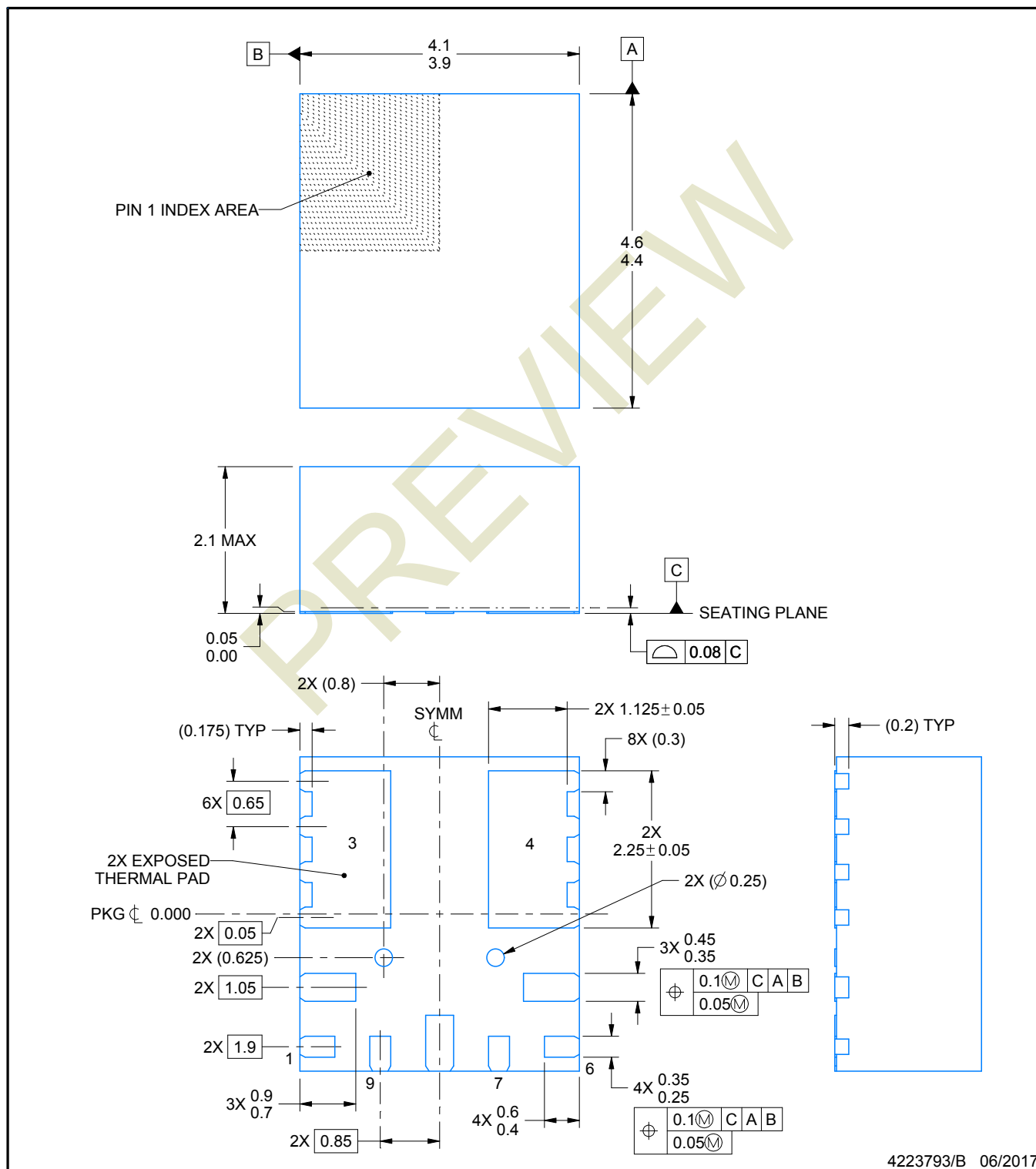
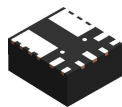


DATA BOOK
PACKAGE OUTLINE

PREVIEW

LEADFRAME EXAMPLE
6609430

DRAFTER:	T. LEQUANG	DATE:	06/26/2017			DIMENSIONS IN MILLIMETERS			
DESIGNER:		DATE:		 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS CODE IDENTITY NUMBER 01295 ePOD, RKH0009A / QFN, 9 PIN, 0.65 MM PITCH					
CHECKER:	K. SINCERBOX	DATE:	2017						
ENGINEER:	C. FERNANDEZ	DATE:	2017						
APPROVED:	D. CHIN & D. BABARAN	DATE:	2017						
RELEASED:	WDM	DATE:	2017						
TEMPLATE INFO:		DATE:		SCALE	SIZE			REV	PAGE
EDGE# 4218519			04/07/2016	NTS	A	4223793		B	1 OF 5



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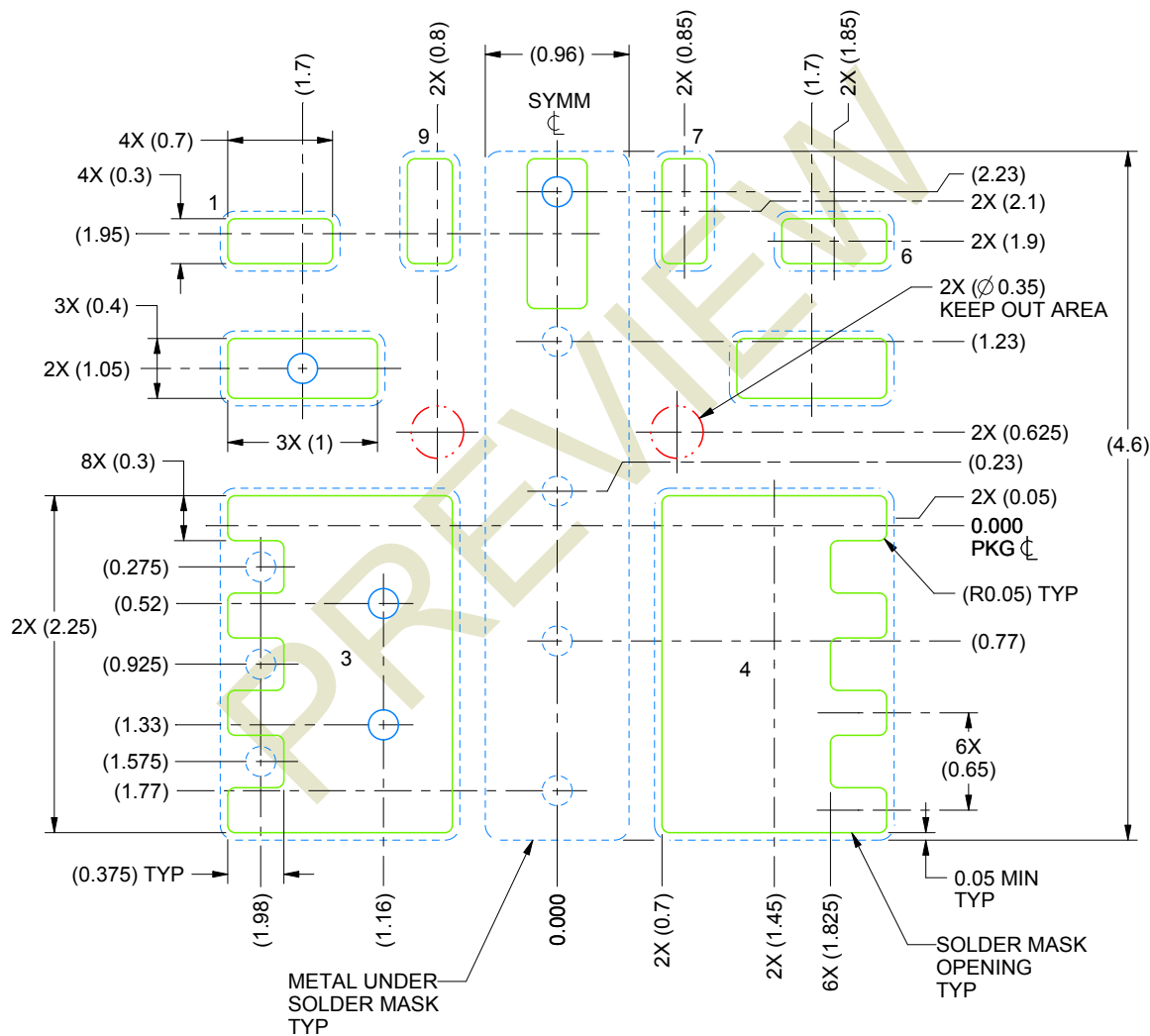
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for thermal and mechanical performance.

RKH0009A

QFN - 2.1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SOLDER MASK DEFINED
SCALE:20X

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NOTES: (continued)

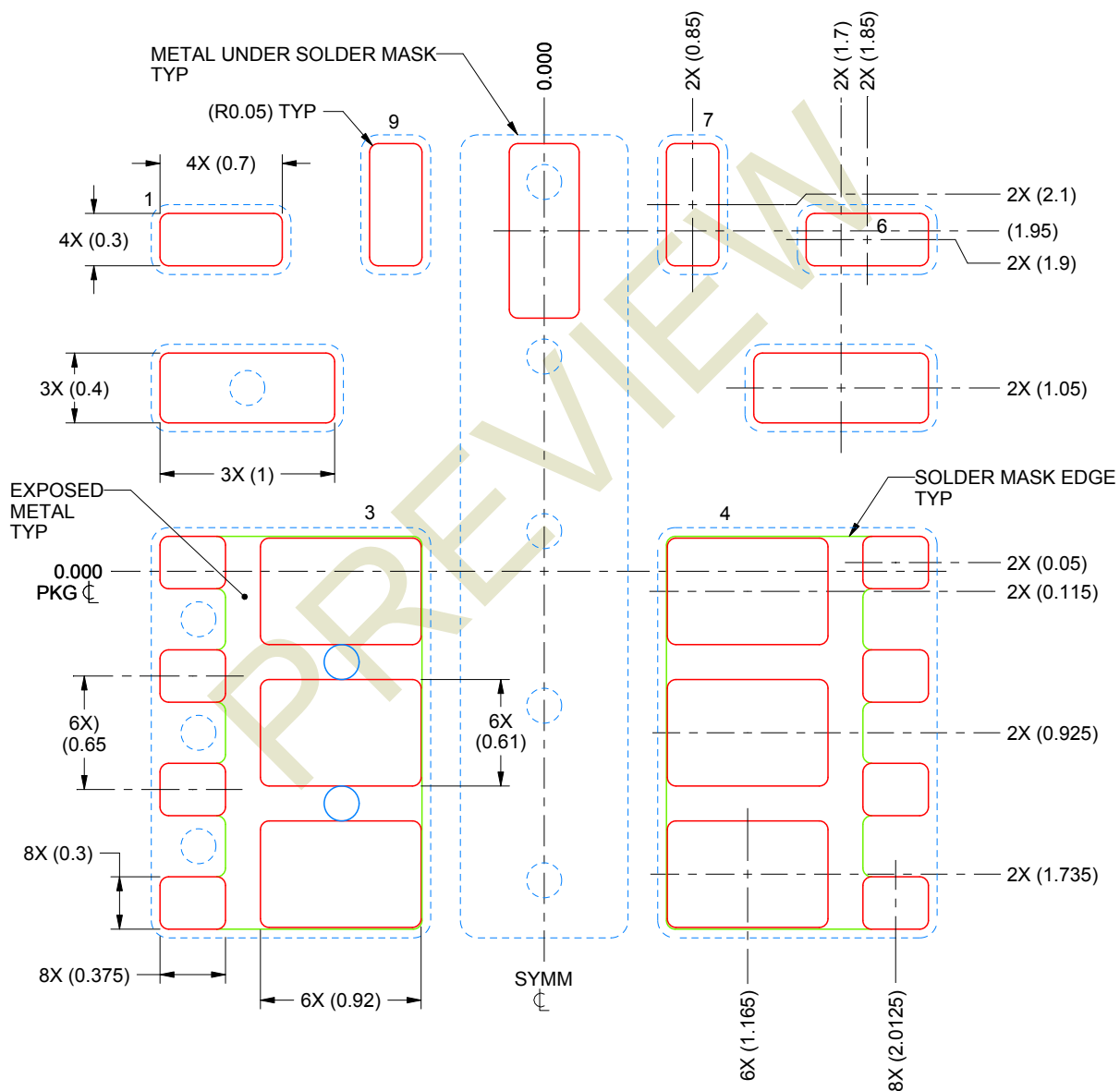
4. This package is designed to be soldered to thermal pads on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RKH0009A

QFN - 2.1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
 PADS 3 & 4: 71%
 SCALE:25X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2166659	06/26/2017	C. FERNANDEZ / T. LEQUANG
B	CHANGE OVERALL TOLERANCE FROM 0.15 to 0.1; CHNAGE PKG NAME TO QFN;	2167964	2017	C. FERNANDEZ / K. SINCERBOX

PREVIEW